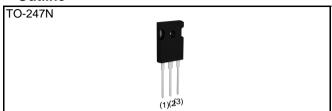


N-channel SiC power MOSFET

| V _{DSS} | 1200V |
|----------------------------|-------|
| R _{DS(on)} (Typ.) | 18mΩ |
| I _D *1 | 81A |
| P_{D} | 312W |

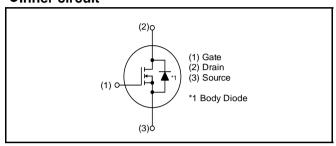
Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

•Inner circuit



Application

- · Solar inverters
- DC/DC converters
- · Switch mode power supplies
- · Induction heating

Packaging specifications

| | Packing | Tube |
|------|---------------------------|-----------|
| | Reel size (mm) | ı |
| Type | Tape width (mm) | - |
| Туре | Basic ordering unit (pcs) | 30 |
| | Taping code | C11 |
| | Marking | SCT4018KE |

● **Absolute maximum ratings** (T_{vj} = 25°C unless otherwise specified.)

| Parameter | | Symbol | Value | Unit | |
|--|--------------------------------------|----------------------------|------------------------------------|------------|---|
| Drain - source voltage | | V_{DSS} | 1200 | V | |
| Continuous drain | $V_{GS} = V_{GS_on}$ | $T_c = 25^{\circ}C$ | I _D , I _S *1 | 81 | А |
| and source current | V _{GS} = V _{GS_on} | T _c = 100°C | I _D , I _S | 57 | А |
| Pulsed drain current | $V_{GS} = V_{GS_on}$ | $T_c = 25^{\circ}C$ | I _{D,pulse} *2 | 179 | А |
| Body diode pulsed forward | ard current | $T_c = 25^{\circ}C$ | I _{S,pulse} *1,*3 | 81 | А |
| Body diode surge forward current $V_{GS} = 0 \text{ V}$ | | I _{S,pulse} *1,*4 | 179 | А | |
| Gate - source voltage (DC) | | V_{GSS_DC} | -4 to +21 | V | |
| Gate - source surge voltage (t _{surge} < 300ns) | | $V_{GSS_surge}^{*5}$ | -4 to +23 | V | |
| Recommended turn-on gate - source drive voltage | | ive voltage | ${\sf V_{GS_on}}^{*6}$ | +15 to +18 | V |
| Recommended turn-off gate - source drive voltage | | V_{GS_off} | 0 | V | |
| Virtual junction temperature | | T_{vj} | 175 | °C | |
| Range of storage temperature | | T_{stg} | -40 to +175 | °C | |

ullet Electrical characteristics (T_{vj} = 25°C unless otherwise specified)

| Parameter | Symbol Conditions | | Values | | | Unit |
|---|------------------------|--|--------|------|------|-------|
| raiailletei | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Drain - Source breakdown | W | $V_{GS} = 0 \text{ V}, I_D = 18.6\text{mA}$ | | | | V |
| voltage | V (BR)DSS | $T_{vj} = 25^{\circ}C$ | 1200 | - | - | V |
| | | $V_{GS} = 0 \text{ V}, V_{DS} = 1200 \text{V}$ | | | | |
| Zero Gate voltage Drain current | I _{DSS} | $T_{vj} = 25^{\circ}C$ | - | 1 | 80 | μA |
| Diam ourion | | T _{vj} = 150°C | - | 10 | - | |
| Gate - Source leakage current | I _{GSS+} | $V_{GS} = +21V , V_{DS} = 0V$ | - | - | 100 | nA |
| Gate - Source leakage current | | $V_{GS} = -4V$, $V_{DS} = 0V$ | ı | ı | -100 | nA |
| Gate threshold voltage | $V_{GS(th)}^{*7}$ | $V_{DS} = 10V, I_D = 22.2mA$ | 2.8 | ı | 4.8 | V |
| | | $V_{GS} = 18V, I_{D} = 42A$ | | | | |
| Static Drain - Source on - state resistance | R _{DS(on)} *8 | $T_{vj} = 25^{\circ}C$ | - | 18.0 | 23.4 | mΩ |
| 5 5 | | T _{vj} = 150°C | - | 36.0 | - | |
| Gate input resistance | R_{G} | f = 1MHz, open drain | - | 1 | - | Ω |

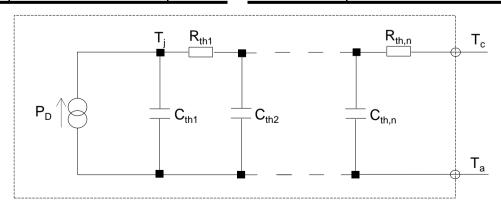
●Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|-------------------------------------|----------------------|--------|------|------|-------|
| Falametei | | Min. | Тур. | Max. | Offic |
| Thermal resistance, junction - case | R _{thJC} *9 | - | 0.37 | 0.48 | K/W |

● Typical Transient Thermal Characteristics

| Symbol | Value | Unit |
|------------------|-----------------------|------|
| R _{th1} | 4.0 ×10 ⁻² | |
| R _{th2} | 1.6 ×10 ⁻¹ | K/W |
| R _{th3} | 1.7 ×10 ⁻¹ | |

| Symbol | Value | Unit |
|------------------|-------------------------------|------|
| C _{th1} | 1.2 ×10 ⁻³ | |
| C_{th2} | 4.6 × 10 ⁻³ | Ws/K |
| C _{th3} | 2.6 ×10 ⁻² | |



ullet Electrical characteristics (T_{vj} = 25°C unless otherwise specified)

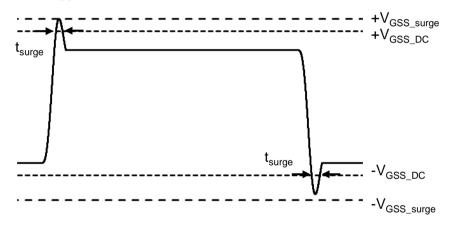
| Dovomotov | Cymada al | Conditions | Values | | | Unit |
|--|------------------------|---|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Transconductance | g _{fs} *8 | $V_{DS} = 10V, I_{D} = 42A$ | - | 22 | - | S |
| Input capacitance | C _{iss} | $V_{GS} = 0V$ | - | 4532 | - | |
| Output capacitance | C _{oss} | V _{DS} = 800V | - | 129 | - | pF |
| Reverse transfer capacitance | C_{rss} | f = 1MHz | - | 9 | - | |
| Effective output capacitance, energy related | C _{o(er)} | $V_{GS} = 0V$ $V_{DS} = 0V \text{ to } 800V$ | - | 156 | - | pF |
| Total Gate charge | Q _g *8 | $V_{DS} = 800V$ $I_{D} = 42A$ | 1 | 170 | ı | |
| Gate - Source charge | Q _{gs} *8 | $V_{GS} = 18V$ | ı | 32 | ı | nC |
| Gate - Drain charge | Q _{gd} *8 | See Fig. 1-1, 1-2. | ı | 52 | ı | |
| Turn - on delay time | t _{d(on)} *8 | $V_{DS} = 800V$ | ı | 15 | ı | |
| Rise time | t _r *8 | $I_D = 42A$ $V_{GS} = +18V / 0V$ | ı | 43 | 1 | ns |
| Turn - off delay time | t _{d(off)} *8 | $R_G = 3.3\Omega$, L = 250µH E_{on} includes diode | - | 50 | - | 113 |
| Fall time | t _f *8 | reverse recovery $L_{\sigma} = 50 \text{nH}, C_{\sigma} = 10 \text{pF}$ | 1 | 14 | 1 | |
| Turn - on switching loss | E _{on} *8 | See Fig. 2-1, 2-2, 2-3. | - | 1100 | - | μJ |
| Turn - off switching loss | E _{off} *8 | | ı | 180 | ı | μο |
| $V_{GS(on)} = +15V$ Short-circuit | - t _{sc} *9 | V _{DS} ≤ 800V V _{DS,peak} ≤ 1200V | - | 4.5 | - | μs |
| withstand time $V_{GS(on)} = +18V$ | | $T_{vj(start)} = 25^{\circ}C$ $R_G = 2.2\Omega$ | - | 4.0 | - | μs |

●Body diode electrical characteristics (Source-Drain) (T_{vi} = 25°C unless otherwise specified)

| Parameter | Symbol Conditions - | Values | | | Unit | |
|-------------------------------|---------------------|--|------|------|------|-------|
| raiailletei | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Forward voltage | V _{SD} *8 | $V_{GS} = 0V, I_{S} = 42A$ | ı | 3.3 | ı | V |
| Reverse recovery time | t _{rr} *8 | $I_F = 42A$ $V_R = 800V$ | ı | 37 | ı | ns |
| Reverse recovery charge | Q _{rr} *8 | di/dt = 2400A/µs | - | 320 | - | nC |
| Peak reverse recovery current | I _{rrm} *8 | $L_{\sigma} = 50$ nH, $C_{\sigma} = 10$ pF See Fig. 3-1, 3-2. | - | 17 | - | А |

^{*1} Limited by maximum T_{vj} and for Max. R_{thJC} .

*5 Example of acceptable V_{GS} waveform



- Please be advised not to use SiC-MOSFETs with V_{GS} below 10V as doing so may cause thermal runaway.
- *7 Tested after applying $V_{GS} = 21V$ for 100ms.
- *8 Pulsed
- *9 The value is based on TO-247 package. Single Pulsed.
- *10 Measured conformable to JESD51-14.

See the application note "rthjc_measurement_and_usage_an-e.pdf". Link

URL: https://fscdn.rohm.com/en/products/databook/applinote/discrete/common/rthjc_measurement_and_usage_an-e.pdf

TSQ50211-SCT4018KE

23.Aug.2023 - Rev.003

^{*2} Pulse width and duty cycle are limited by T_{vi,max}.

^{*3} Only for body-diode, Repititive pulse, PW ≤ 1.5µs, Duty cycle ≤ 5%

^{*4} When used as a protective function, PW ≤ 10µs

Fig.1 Power Dissipation Derating Curve

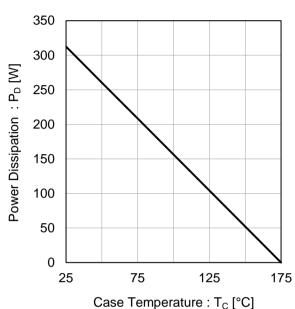


Fig.2 Maximum Safe Operating Area

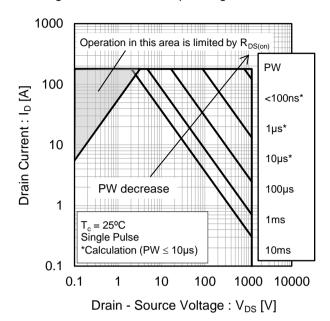
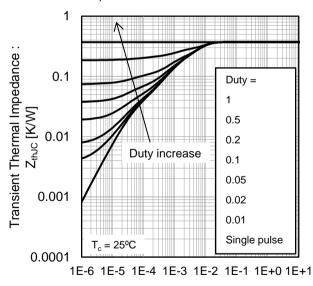


Fig.3 Typical Transient Thermal Impedance vs. Pulse Width



Pulse Width: PW [s]

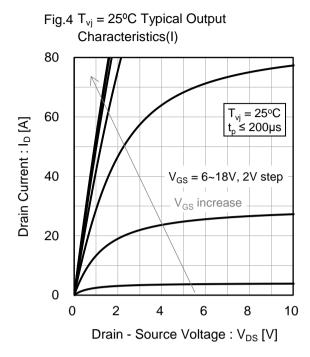
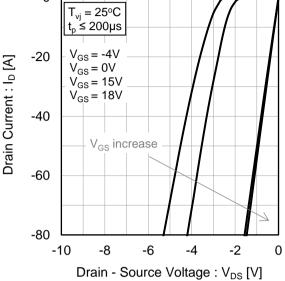
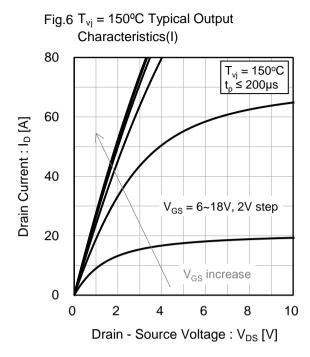
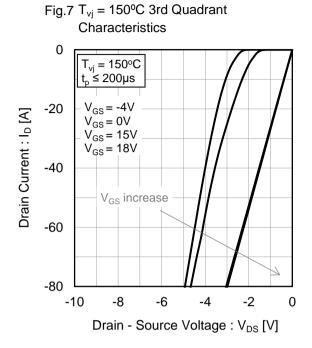


Fig.5 $T_{vj} = 25^{\circ}C$ 3rd Quadrant Characteristics



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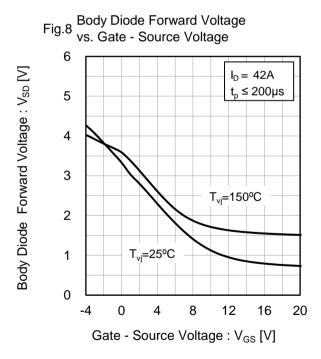


Fig.9 Typical Transfer Characteristics (I)

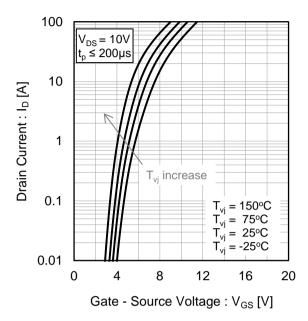


Fig.10 Typical Transfer Characteristics (II)

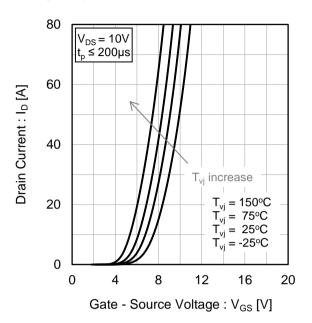


Fig.11 Gate Threshold Voltage vs. Virtual Junction Temperature

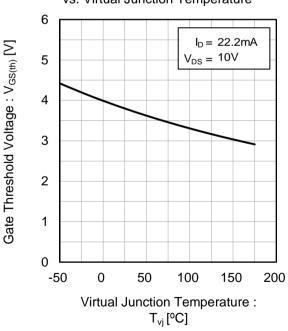


Fig.12 Transconductance vs. Drain Current

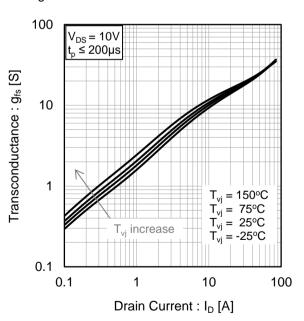


Fig.13 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

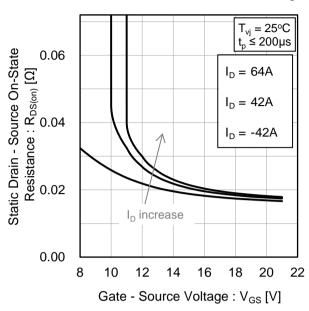


Fig.14 Static Drain - Source On - State Resistance vs. Virtual Junction Temperature

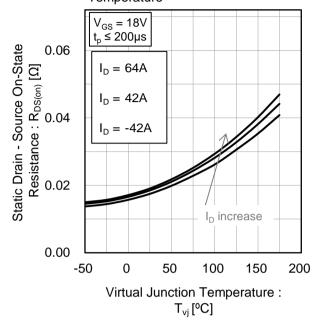


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current

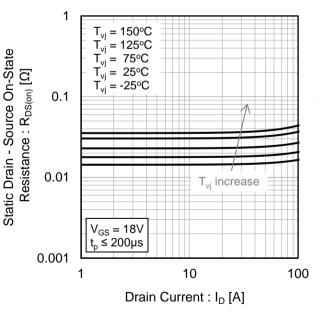
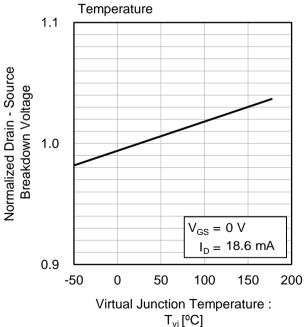
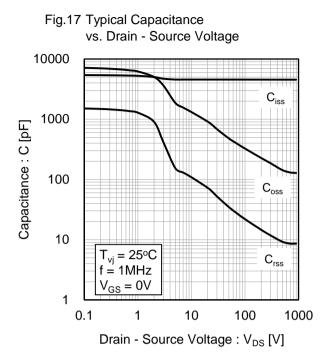


Fig.16 Normalized Drain - Source Breakdown Voltage vs. Virtual Junction





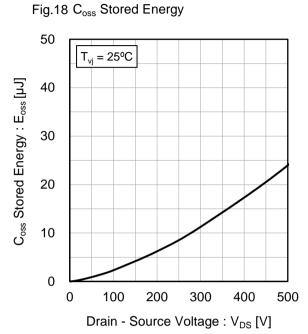


Fig.19 Dynamic Input Characteristics

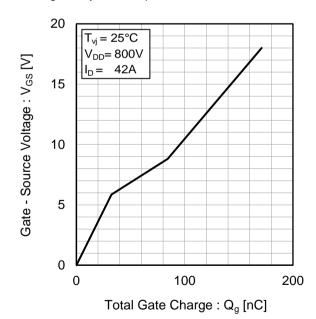
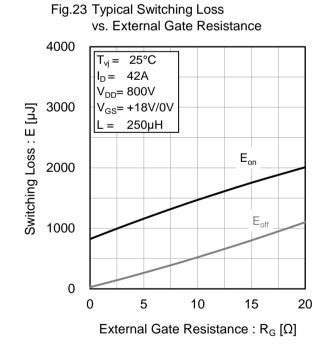


Fig.20 Typical Switching Time vs. External Gate Resistance 200 $T_{vi} = 25^{\circ}C$ $I_D = 42A$ $t_{d(off)}$ V_{DD}= 800V 150 $V_{GS} = +18V/0V$ Switching Time : t [ns] $L = 250 \mu H$ $t_{d(on)}$ 100 $t_{\rm f}$ 50 0 5 10 15 20 External Gate Resistance : $R_G[\Omega]$

vs. Drain - Source Voltage 4000 $T_{vi} = 25^{\circ}C$ 42A V_{GS}= +18V/0V 3000 $R_G = 3.3\Omega$ Switching Loss : E [µJ] $L = 250 \mu H$ 2000 E_{on} 1000 $\mathsf{E}_{\mathsf{off}}$ 0 100 200 300 400 500 600 700 800 Drain - Source Voltage: V_{DS} [V]

Fig.21 Typical Switching Loss

Fig.22 Typical Switching Loss vs. Drain Current 4000 $T_{vj} =$ 25°C $V_{DD} = 800V$ $V_{GS} = +18V/0V$ $R_G = 3.3\Omega$ 3000 Switching Loss : E [µJ] 250µH 2000 E_{on} 1000 $\mathsf{E}_{\mathrm{off}}$ 0 10 30 40 50 70 80 Drain Current: I_D [A]



• Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

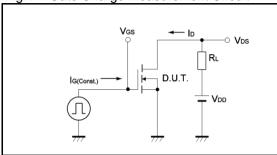


Fig.2-1 Switching Characteristics Measurement Circuit

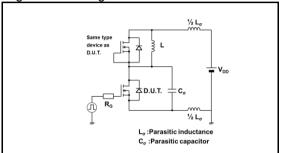


Fig.2-3 Waveforms for Switching Energy Loss

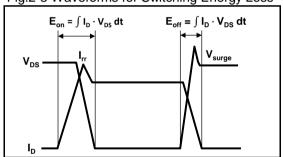


Fig.3-1 Reverse Recovery Time Measurement Circuit

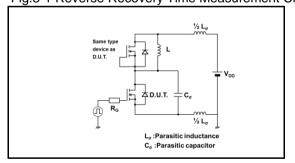


Fig.1-2 Gate Charge Waveform

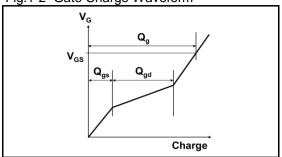


Fig.2-2 Waveforms for Switching Time

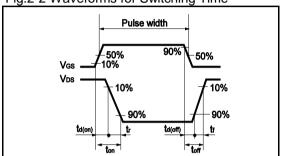
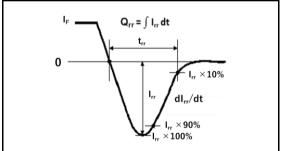
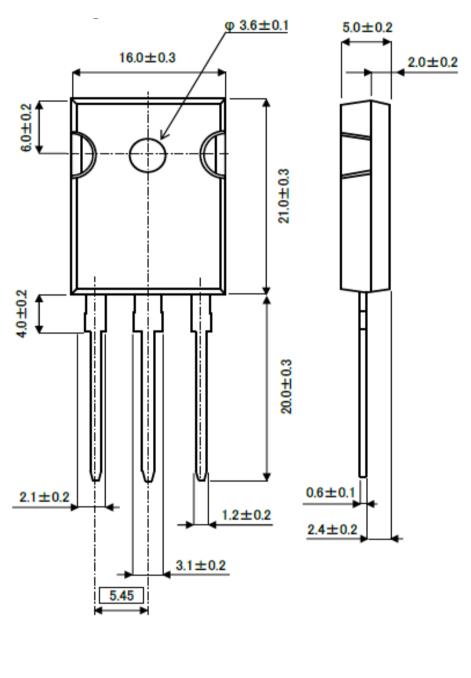


Fig.3-2 Reverse Recovery Waveform

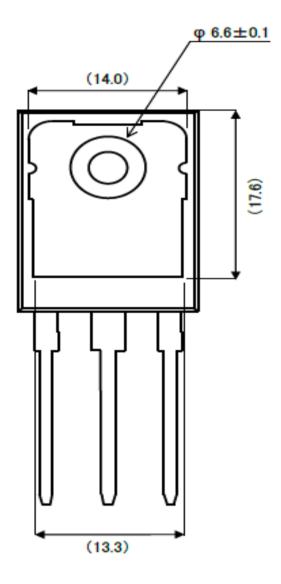


Package Dimensions



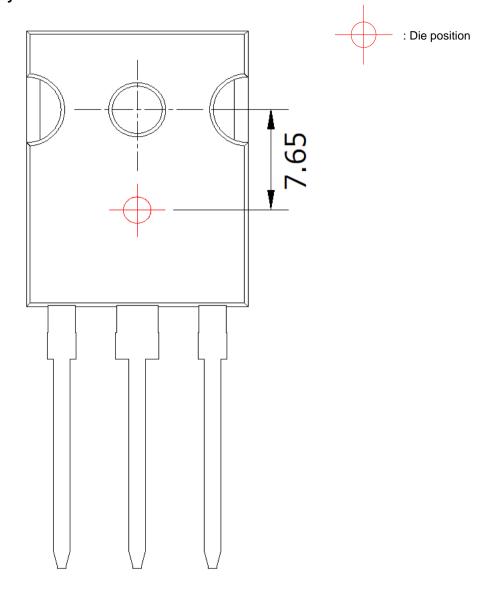


Unit: mm



Unit: mm

●Die Bonding Layout



- •Front view of the packaging.
- •Dimensions are design values.
- ·If the heat sink is to be installed, it should be in contact with the die bonding point.

Unit: mm

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